

CD4011BMS, CD4012BMS, CD4023BMS

CMOS NAND Gates

FN3079
Rev 0.00
November 1994

Features

- High-Voltage Types (20V Rating)
- Propagation Delay Time = 60ns (typ.) at CL = 50pF, VDD = 10V
- Buffered Inputs and Outputs
- Standardized Symmetrical Output Characteristics
- Maximum Input Current of 1 μ A at 18V Over Full Package-Temperature Range; 100nA at 18V and +25 $^{\circ}$ C
- 100% Tested for Maximum Quiescent Current at 20V
- 5V, 10V and 15V Parametric Ratings
- Noise Margin (Over Full Package Temperature Range):
 - 1V at VDD = 5V
 - 2V at VDD = 10V
 - 2.5V at VDD = 15V
- Meets All Requirements of JEDEC Tentative Standards No. 13B, "Standard Specifications for Description of "B" Series CMOS Device's

Description

CD4011BMS - Quad 2 Input

CD4012BMS - Dual 4 Input

CD4023BMS - Triple 3 Input

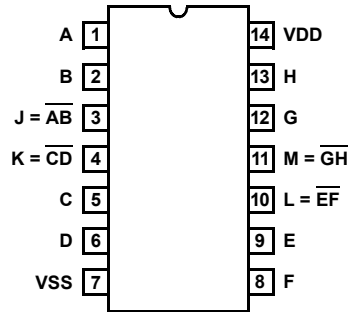
CD4011BMS, CD4012BMS, and CD4023BMS NAND gates provide the system designer with direct implementation of the NAND function and supplement the existing family of CMOS gates. All inputs and outputs are buffered.

The CD4011BMS, CD4012BMS and the CD4023BMS is supplied in these 14 lead outline packages:

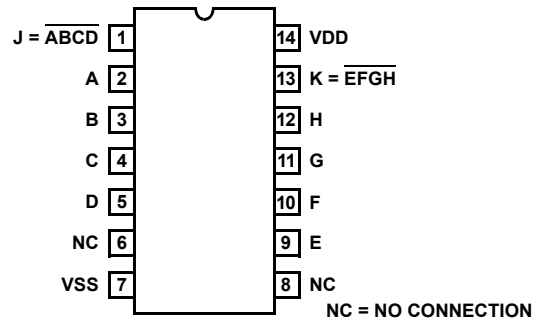
| | CD4011B | CD4012B | CD4023B |
|------------------|---------|---------|---------|
| Braze Seal DIP | H4Q | H4H | H4Q |
| Frit Seal DIP | H1B | H1B | H1B |
| Ceramic Flatpack | H3W | H3W | H3W |

Pinouts

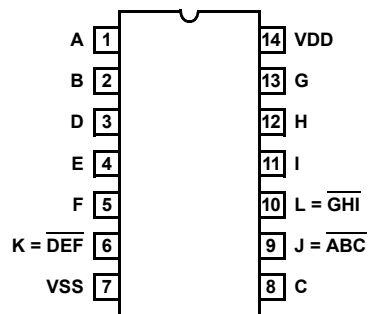
CD4011BMS
TOP VIEW



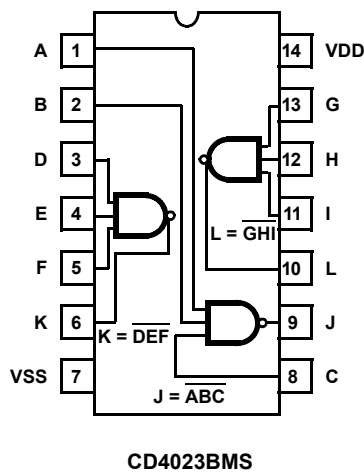
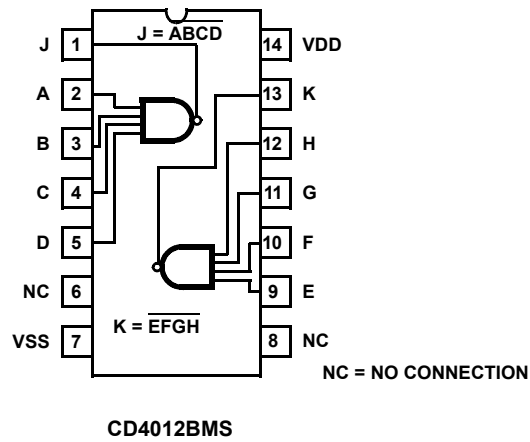
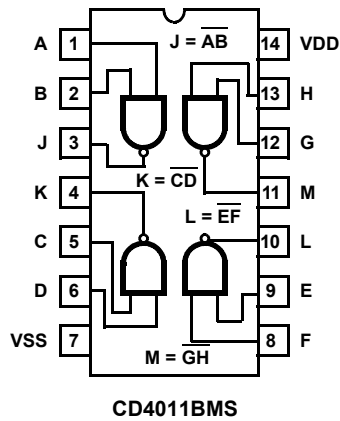
CD4012BMS
TOP VIEW



CD4023BMS
TOP VIEW



Functional Diagrams



Absolute Maximum Ratings

DC Supply Voltage Range, (VDD) -0.5V to +20V
 (Voltage Referenced to VSS Terminals)
 Input Voltage Range, All Inputs-0.5V to VDD +0.5V
 DC Input Current, Any One Input±10mA
 Operating Temperature Range.....-55°C to +125°C
 Package Types D, F, K, H
 Storage Temperature Range (TSTG) -65°C to +150°C
 Lead Temperature (During Soldering) +265°C
 At Distance 1/16 ± 1/32 Inch (1.59mm ± 0.79mm) from case for
 10s Maximum

Reliability Information

Thermal Resistance θ_{ja} θ_{jc}
 Ceramic DIP and FRIT Package 80°C/W 20°C/W
 Flatpack Package 70°C/W 20°C/W
 Maximum Package Power Dissipation (PD) at +125°C
 For TA = -55°C to +100°C (Package Type D, F, K) 500mW
 For TA = +100°C to +125°C (Package Type D, F, K) Derate
 Linearity at 12mW/°C to 200mW
 Device Dissipation per Output Transistor 100mW
 For TA = Full Package Temperature Range (All Package Types)
 Junction Temperature +175°C

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

| PARAMETER | SYMBOL | CONDITIONS (NOTE 1) | | GROUP A SUBGROUPS | TEMPERATURE | LIMITS | | UNITS |
|-----------------------------|--------|------------------------------------|-----------|-------------------|----------------------|-------------|-------------|-------|
| | | | | | | MIN | MAX | |
| Supply Current | IDD | VDD = 20V, VIN = VDD or GND | | 1 | +25°C | - | 0.5 | µA |
| | | | | 2 | +125°C | - | 50 | µA |
| | | VDD = 18V, VIN = VDD or GND | | 3 | -55°C | - | 0.5 | µA |
| Input Leakage Current | IIL | VIN = VDD or GND | VDD = 20 | 1 | +25°C | -100 | - | nA |
| | | | VDD = 18V | 2 | +125°C | -1000 | - | nA |
| | | | | 3 | -55°C | -100 | - | nA |
| Input Leakage Current | IIH | VIN = VDD or GND | VDD = 20 | 1 | +25°C | - | 100 | nA |
| | | | VDD = 18V | 2 | +125°C | - | 1000 | nA |
| | | | | 3 | -55°C | - | 100 | nA |
| Output Voltage | VOL15 | VDD = 15V, No Load | | 1, 2, 3 | +25°C, +125°C, -55°C | - | 50 | mV |
| Output Voltage | VOH15 | VDD = 15V, No Load (Note 3) | | 1, 2, 3 | +25°C, +125°C, -55°C | 14.95 | - | V |
| Output Current (Sink) | IOL5 | VDD = 5V, VOUT = 0.4V | | 1 | +25°C | 0.53 | - | mA |
| Output Current (Sink) | IOL10 | VDD = 10V, VOUT = 0.5V | | 1 | +25°C | 1.4 | - | mA |
| Output Current (Sink) | IOL15 | VDD = 15V, VOUT = 1.5V | | 1 | +25°C | 3.5 | - | mA |
| Output Current (Source) | IOH5A | VDD = 5V, VOUT = 4.6V | | 1 | +25°C | - | -0.53 | mA |
| Output Current (Source) | IOH5B | VDD = 5V, VOUT = 2.5V | | 1 | +25°C | - | -1.8 | mA |
| Output Current (Source) | IOH10 | VDD = 10V, VOUT = 9.5V | | 1 | +25°C | - | -1.4 | mA |
| Output Current (Source) | IOH15 | VDD = 15V, VOUT = 13.5V | | 1 | +25°C | - | -3.5 | mA |
| N Threshold Voltage | VNTH | VDD = 10V, ISS = -10µA | | 1 | +25°C | -2.8 | -0.7 | V |
| P Threshold Voltage | VPTH | VSS = 0V, IDD = 10µA | | 1 | +25°C | 0.7 | 2.8 | V |
| Functional | F | VDD = 2.8V, VIN = VDD or GND | | 7 | +25°C | VOH > VDD/2 | VOL < VDD/2 | V |
| | | VDD = 20V, VIN = VDD or GND | | 7 | +25°C | | | |
| | | VDD = 18V, VIN = VDD or GND | | 8A | +125°C | | | |
| | | VDD = 3V, VIN = VDD or GND | | 8B | -55°C | | | |
| Input Voltage Low (Note 2) | VIL | VDD = 5V, VOH > 4.5V, VOL < 0.5V | | 1, 2, 3 | +25°C, +125°C, -55°C | - | 1.5 | V |
| Input Voltage High (Note 2) | VIH | VDD = 5V, VOH > 4.5V, VOL < 0.5V | | 1, 2, 3 | +25°C, +125°C, -55°C | 3.5 | - | V |
| Input Voltage Low (Note 2) | VIL | VDD = 15V, VOH > 13.5V, VOL < 1.5V | | 1, 2, 3 | +25°C, +125°C, -55°C | - | 4 | V |
| Input Voltage High (Note 2) | VIH | VDD = 15V, VOH > 13.5V, VOL < 1.5V | | 1, 2, 3 | +25°C, +125°C, -55°C | 11 | - | V |

NOTES: 1. All voltages referenced to device GND, 100% testing being implemented. 2. Go/No Go test with limits applied to inputs 3. For accuracy, voltage is measured differentially to VDD. Limit is 0.050V max.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

| PARAMETER | SYMBOL | CONDITIONS (NOTE 1, 2) | GROUP A SUBGROUPS | TEMPERATURE | LIMITS | | UNITS |
|-------------------|--------------|----------------------------|----------------------|---------------|--------|-----|-------|
| | | | | | MIN | MAX | |
| Propagation Delay | TPHL TPLH | VDD = 5V, VIN = VDD or GND | 9 | +25°C | - | 250 | ns |
| | | | 10, 11 | +125°C, -55°C | - | 338 | ns |
| Transition Time | TTHL TTLH | VDD = 5V, VIN = VDD or GND | 9 | +25°C | - | 200 | ns |
| | | | 10, 11 | +125°C, -55°C | - | 270 | ns |

NOTES:

1. CL = 50pF, RL = 200K, Input TR, TF < 20ns.
2. -55°C and +125°C limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

| PARAMETER | SYMBOL | CONDITIONS | NOTES | TEMPERATURE | LIMITS | | UNITS |
|-----------------------------|--------------|-------------------------------|---------|-------------------------|--------|-------|-------|
| | | | | | MIN | MAX | |
| Supply Current | IDD | VDD = 5V, VIN = VDD or GND | 1, 2 | -55°C, +25°C | - | 0.25 | μA |
| | | | | +125°C | - | 7.5 | μA |
| | | VDD = 10V, VIN = VDD or GND | 1, 2 | -55°C, +25°C | - | 0.5 | μA |
| | | | | +125°C | - | 15 | μA |
| VDD = 15V, VIN = VDD or GND | 1, 2 | -55°C, +25°C | - | 0.5 | μA | | |
| | | +125°C | - | 30 | μA | | |
| Output Voltage | VOL | VDD = 5V, No Load | 1, 2 | +25°C, +125°C, -55°C | - | 50 | mV |
| Output Voltage | VOL | VDD = 10V, No Load | 1, 2 | +25°C, +125°C, -55°C | - | 50 | mV |
| Output Voltage | VOH | VDD = 5V, No Load | 1, 2 | +25°C, +125°C, -55°C | 4.95 | - | V |
| Output Voltage | VOH | VDD = 10V, No Load | 1, 2 | +25°C, +125°C, -55°C | 9.95 | - | V |
| Output Current (Sink) | IOL5 | VDD = 5V, VOUT = 0.4V | 1, 2 | +125°C | 0.36 | - | mA |
| | | | | -55°C | 0.64 | - | mA |
| Output Current (Sink) | IOL10 | VDD = 10V, VOUT = 0.5V | 1, 2 | +125°C | 0.9 | - | mA |
| | | | | -55°C | 1.6 | - | mA |
| Output Current (Sink) | IOL15 | VDD = 15V, VOUT = 1.5V | 1, 2 | +125°C | 2.4 | - | mA |
| | | | | -55°C | 4.2 | - | mA |
| Output Current (Source) | IOH5A | VDD = 5V, VOUT = 4.6V | 1, 2 | +125°C | - | -0.36 | mA |
| | | | | -55°C | - | -0.64 | mA |
| Output Current (Source) | IOH5B | VDD = 5V, VOUT = 2.5V | 1, 2 | +125°C | - | -1.15 | mA |
| | | | | -55°C | - | -2.0 | mA |
| Output Current (Source) | IOH10 | VDD = 10V, VOUT = 9.5V | 1, 2 | +125°C | - | -0.9 | mA |
| | | | | -55°C | - | -1.6 | mA |
| Output Current (Source) | IOH15 | VDD = 15V, VOUT = 13.5V | 1, 2 | +125°C | - | -2.4 | mA |
| | | | | -55°C | - | -4.2 | mA |
| Input Voltage Low | VIL | VDD = 10V, VOH > 9V, VOL < 1V | 1, 2 | +25°C, +125°C, -55°C | - | 3 | V |
| Input Voltage High | VIH | VDD = 10V, VOH > 9V, VOL < 1V | 1, 2 | +25°C, +125°C, -55°C | 7 | - | V |
| Propagation Delay | TPHL TPLH | VDD = 10V | 1, 2, 3 | +25°C | - | 120 | ns |
| | | VDD = 15V | 1, 2, 3 | +25°C | - | 90 | ns |
| Transition Time | TTHL TTLH | VDD = 10V | 1, 2, 3 | +25°C | - | 100 | ns |
| | | VDD = 15V | 1, 2, 3 | +25°C | - | 80 | ns |

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

| PARAMETER | SYMBOL | CONDITIONS | NOTES | TEMPERATURE | LIMITS | | UNITS |
|-------------------|--------|------------|-------|-------------|--------|-----|-------|
| | | | | | MIN | MAX | |
| Input Capacitance | CIN | Any Input | 1, 2 | +25°C | - | 7.5 | pF |

NOTES:

1. All voltages referenced to device GND.
2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

| PARAMETER | SYMBOL | CONDITIONS | NOTES | TEMPERATURE | LIMITS | | UNITS |
|---------------------------|--------------------------------------|---|------------|-------------|-------------|--------------------|-------|
| | | | | | MIN | MAX | |
| Supply Current | IDD | VDD = 20V, VIN = VDD or GND | 1, 4 | +25°C | - | 2.5 | µA |
| N Threshold Voltage | VNTH | VDD = 10V, ISS = -10µA | 1, 4 | +25°C | -2.8 | -0.2 | V |
| N Threshold Voltage Delta | ΔVNTH | VDD = 10V, ISS = -10µA | 1, 4 | +25°C | - | ±1 | V |
| P Threshold Voltage | VPTH | VSS = 0V, IDD = 10µA | 1, 4 | +25°C | 0.2 | 2.8 | V |
| P Threshold Voltage Delta | ΔVPTH | VSS = 0V, IDD = 10µA | 1, 4 | +25°C | - | ±1 | V |
| Functional | F | VDD = 18V, VIN = VDD or GND VDD = 3V, VIN = VDD or GND | 1 | +25°C | VOH > VDD/2 | VOL < VDD/2 | V |
| Propagation Delay Time | T _{PHL} T _{PLH} | VDD = 5V | 1, 2, 3, 4 | +25°C | - | 1.35 x +25°C Limit | ns |

- NOTES: 1. All voltages referenced to device GND. 2. CL = 50pF, RL = 200K, Input TR, TF < 20ns. 3. See Table 2 for +25°C limit. 4. Read and Record

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

| PARAMETER | SYMBOL | DELTA LIMIT |
|-------------------------|--------|--------------------------|
| Supply Current - SSI | IDD | ± 0.1µA |
| Output Current (Sink) | IOL5 | ± 20% x Pre-Test Reading |
| Output Current (Source) | IOH5A | ± 20% x Pre-Test Reading |

TABLE 6. APPLICABLE SUBGROUPS

| CONFORMANCE GROUP | MIL-STD-883 METHOD | GROUP A SUBGROUPS | READ AND RECORD |
|-------------------------------|--------------------|-------------------------------|------------------------------|
| Initial Test (Pre Burn-In) | 100% 5004 | 1, 7, 9 | IDD, IOL5, IOH5A |
| Interim Test 1 (Post Burn-In) | 100% 5004 | 1, 7, 9 | IDD, IOL5, IOH5A |
| Interim Test 2 (Post Burn-In) | 100% 5004 | 1, 7, 9 | IDD, IOL5, IOH5A |
| PDA (Note 1) | 100% 5004 | 1, 7, 9, Deltas | |
| Interim Test 3 (Post Burn-In) | 100% 5004 | 1, 7, 9 | IDD, IOL5, IOH5A |
| PDA (Note 1) | 100% 5004 | 1, 7, 9, Deltas | |
| Final Test | 100% 5004 | 2, 3, 8A, 8B, 10, 11 | |
| Group A | Sample 5005 | 1, 2, 3, 7, 8A, 8B, 9, 10, 11 | |
| Group B | Subgroup B-5 | Sample 5005 | Subgroups 1, 2, 3, 9, 10, 11 |
| | Subgroup B-6 | Sample 5005 | 1, 7, 9 |
| Group D | Sample 5005 | 1, 2, 3, 8A, 8B, 9 | Subgroups 1, 2 3 |

NOTE: 1. 5% Parametric, 3% Functional; Cumulative for Static 1 and 2.

TABLE 7. TOTAL DOSE IRRADIATION

| CONFORMANCE GROUPS | MIL-STD-883 METHOD | TEST | | READ AND RECORD | |
|--------------------|--------------------|-----------|------------|-----------------|------------|
| | | PRE-IRRAD | POST-IRRAD | PRE-IRRAD | POST-IRRAD |
| Group E Subgroup 2 | 5005 | 1, 7, 9 | Table 4 | 1, 9 | Table 4 |

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS

| FUNCTION | OPEN | GROUND | VDD | 9V ± -0.5V | OSCILLATOR | |
|----------------------------|--------------|----------------------|------------------------------|--------------|-----------------------------|-------|
| | | | | | 50kHz | 25kHz |
| PART NUMBER CD4011B | | | | | | |
| Static Burn-In 1 Note 1 | 3, 4, 10, 11 | 1, 2, 5 - 9, 12, 13 | 14 | | | |
| Static Burn-In 2 Note 1 | 3, 4, 10, 11 | 7 | 1, 2, 5, 6, 8, 9, 12 - 14 | | | |
| Dynamic Burn-In Note 1 | - | 7 | 14 | 3, 4, 10, 11 | 1, 2, 5, 6, 8, 9, 12, 13 | |
| Irradiation Note 2 | 3, 4, 10, 11 | 7 | 1, 2, 5, 6, 8, 9, 12 - 14 | | | |
| PART NUMBER CD4012B | | | | | | |
| Static Burn-In 1 Note 1 | 1, 6, 8, 13 | 2 - 5, 7, 9 - 12 | 14 | | | |
| Static Burn-In 2 Note 1 | 1, 6, 8, 13 | 7 | 2 - 5, 9 - 12, 14 | | | |
| Dynamic Burn-In Note 1 | 6, 8 | 7 | 14 | 1, 13 | 2 - 5, 9 - 12 | |
| Irradiation Note 2 | 1, 6, 8, 13 | 7 | 2 - 5, 9 - 12, 14 | | | |
| PART NUMBER CD4023B | | | | | | |
| Static Burn-In 1 Note 1 | 6, 9, 10 | 1 - 5, 7, 8, 11 - 13 | 14 | | | |
| Static Burn-In 2 Note 1 | 6, 9, 10 | 7 | 1 - 5, 8, 11 - 14 | | | |
| Dynamic Burn-In Note 1 | - | 7 | 14 | 6, 9, 10 | 1 - 5, 8, 11 - 13 | |
| Irradiation Note 2 | 6, 9, 10 | 7 | 1 - 5, 8, 11 - 14 | | | |

NOTE:

1. Each pin except VDD and GND will have a series resistor of 10K ± 5%, VDD = 18V ± 0.5V
2. Each pin except VDD and GND will have a series resistor of 47K ± 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = 10V ± 0.5V

© Copyright Intersil Americas LLC 1999. All Rights Reserved.

All trademarks and registered trademarks are the property of their respective owners.

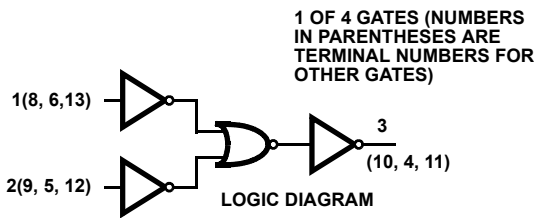
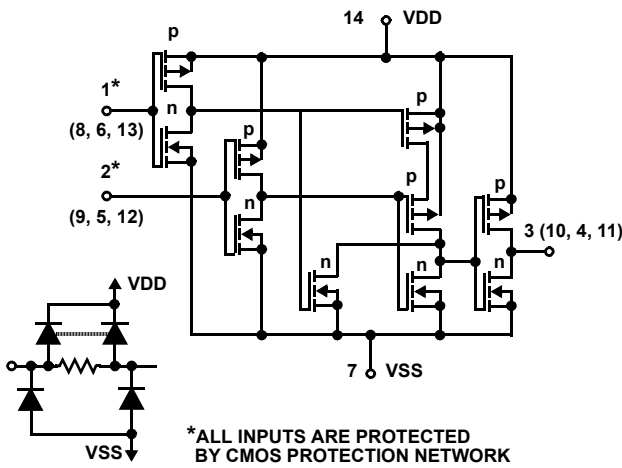
For additional products, see www.intersil.com/en/products.html

Intersil products are manufactured, assembled and tested utilizing ISO9001 quality systems as noted in the quality certifications found at www.intersil.com/en/support/qualandreliability.html

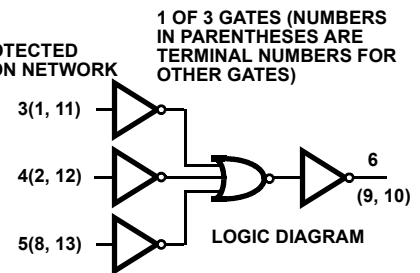
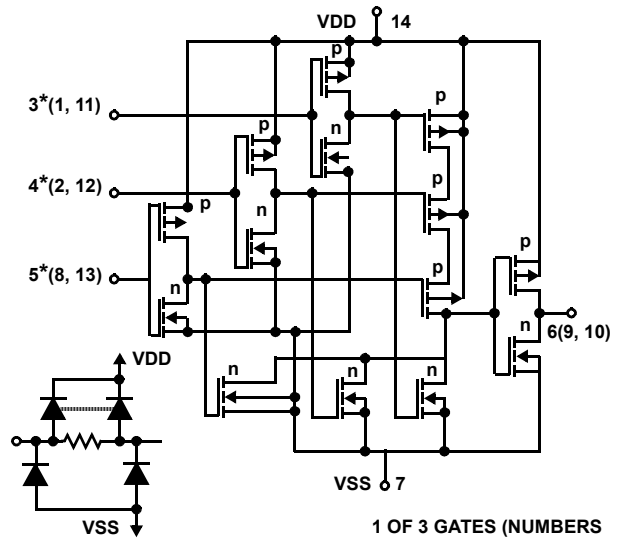
Intersil products are sold by description only. Intersil may modify the circuit design and/or specifications of products at any time without notice, provided that such modification does not, in Intersil's sole judgment, affect the form, fit or function of the product. Accordingly, the reader is cautioned to verify that datasheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see www.intersil.com

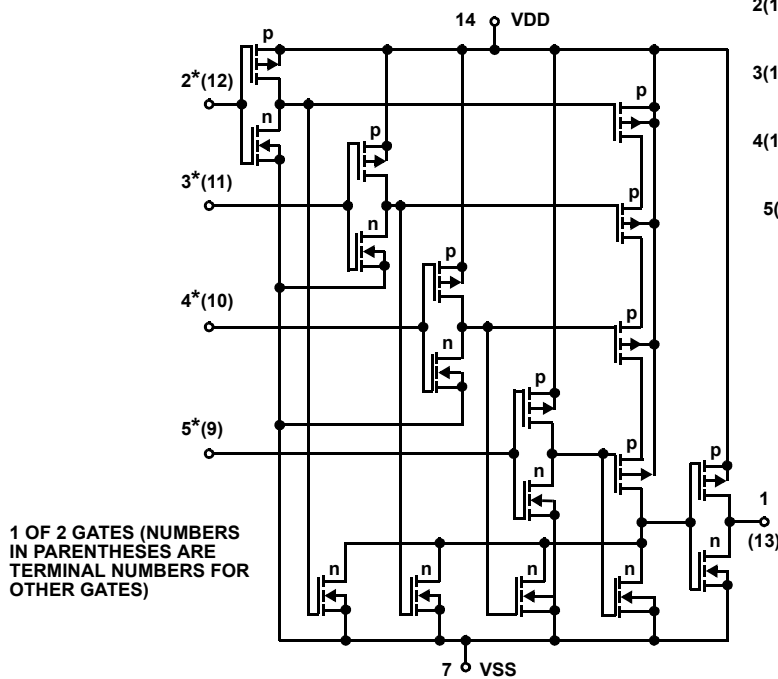
Schematic and Logic Diagrams



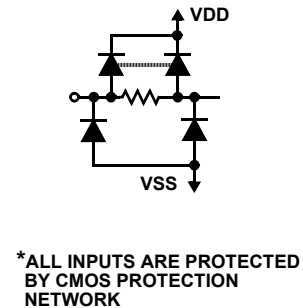
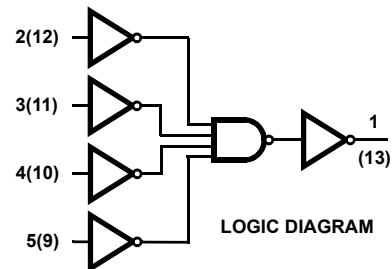
CD4011BMS



CD4023BMS



CD4012BMS



Typical Performance Characteristics

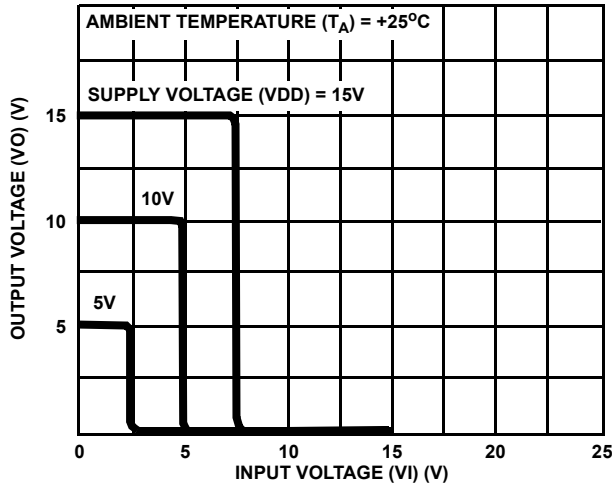


FIGURE 1. TYPICAL VOLTAGE TRANSFER CHARACTERISTICS

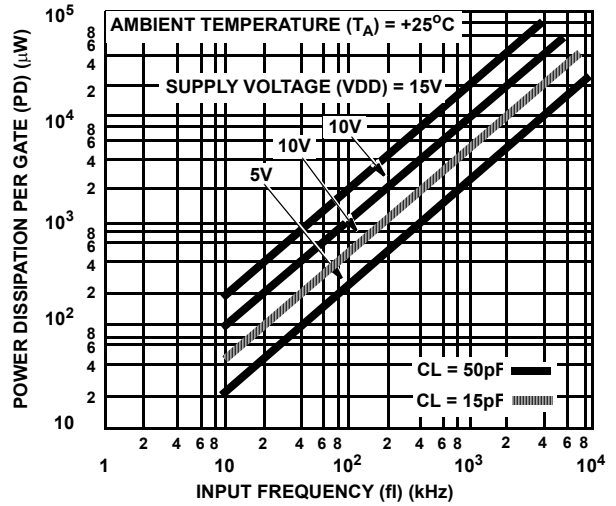


FIGURE 2. TYPICAL POWER DISSIPATION CHARACTERISTICS

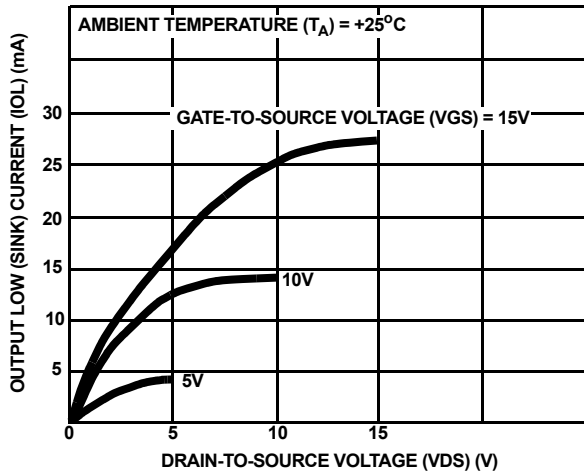


FIGURE 3. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

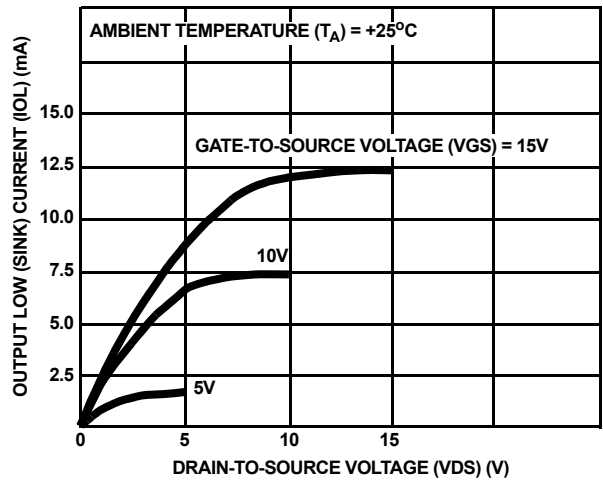


FIGURE 4. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

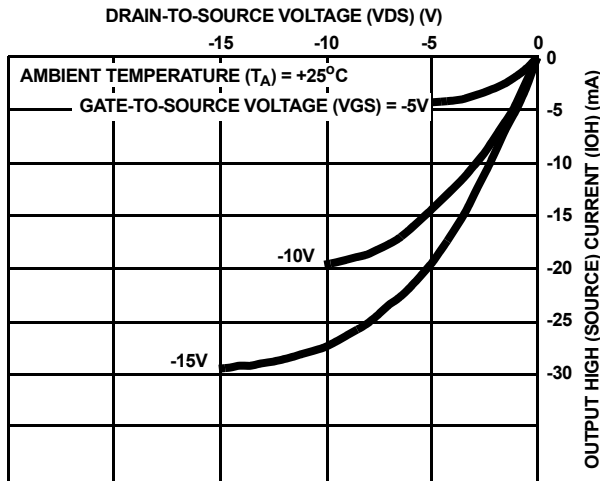


FIGURE 5. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

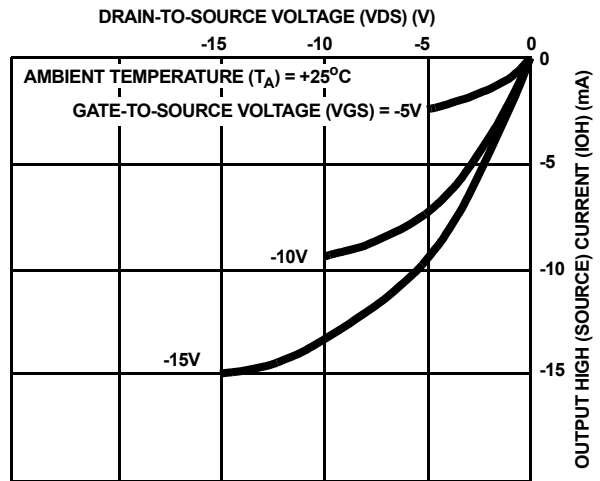


FIGURE 6. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

Typical Performance Characteristics (Continued)

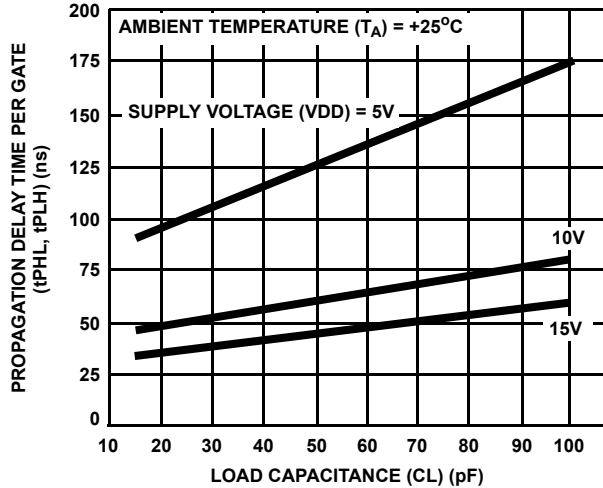


FIGURE 7. TYPICAL PROPAGATION DELAY TIME PER GATE AS A FUNCTION OF LOAD CAPACITANCE

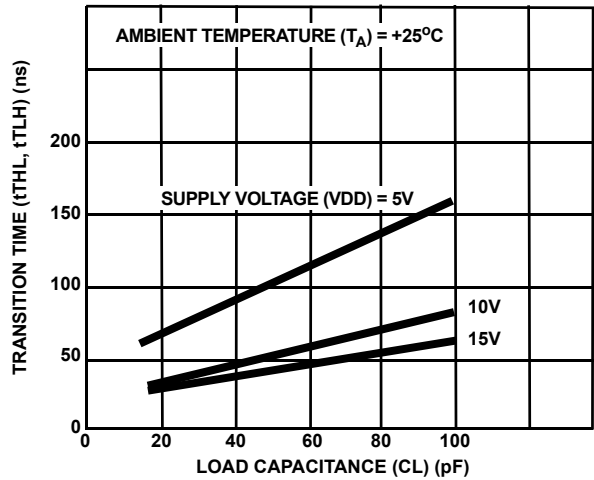
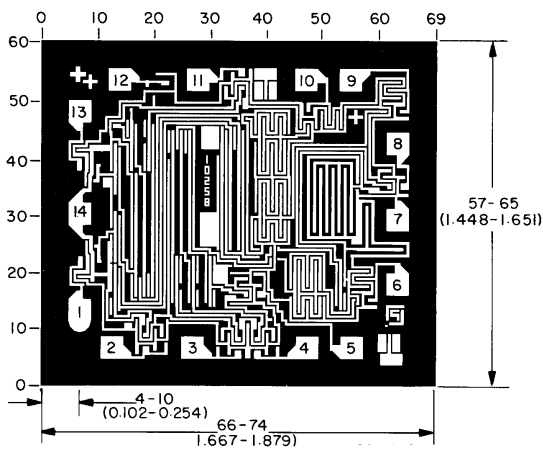
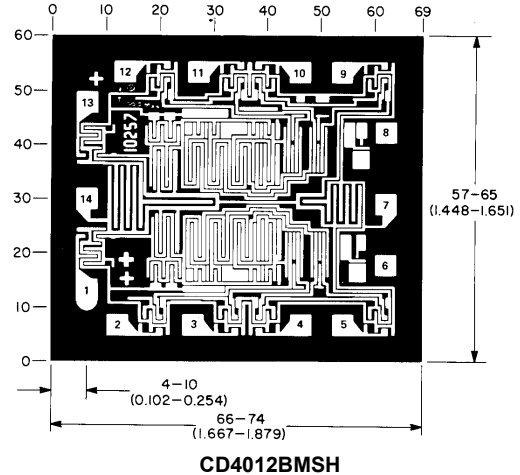
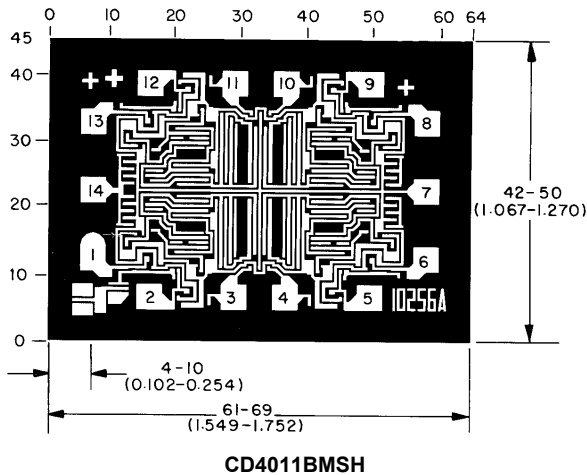


FIGURE 8. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

Chip Dimensions and Pad Layouts



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch)

- METALLIZATION:** Thickness: $11\text{k}\text{\AA}$ – $14\text{k}\text{\AA}$, AL.
- PASSIVATION:** $10.4\text{k}\text{\AA}$ – $15.6\text{k}\text{\AA}$, Silane
- BOND PADS:** 0.004 inches X 0.004 inches MIN
- DIE THICKNESS:** 0.0198 inches - 0.0218 inches